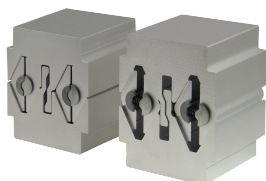


## INTERSCALE FLEXIBLE HEAT CONDUCTOR (FHC), 70 MM



Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

### CERTIFICATIONS



### FEATURES

Designed for ATX/ITX/Mini ITX & COM using Intel core-iprocessors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1156, LGA1366,LGA2011 ; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)

Compatible with Interscale C enclosures

Provides industry leading conduction cooling performance, 70% improvement over current conduction cooling methods

Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad

Secured to PCB with mounting brackets, sold separately

### SPECIFICATIONS

Table 1/2

Catalog Number	Package Quantity	Product Type	Product Family	Works With	Type	Width
24830-001	1	Conductor Block	Interscale	Cases	Heat Conductor	50 mm

Table 2/2

Catalog Number	Depth
24830-001	50 mm

## ADDITIONAL PRODUCT DETAILS

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Please order the mounting bracket (Intel or AMD, listed under accessories) to assemble the FHC to the board.

## WARNING

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nVent products shall be installed and used only as indicated in nVent's product instruction sheets and training materials. Instruction sheets are available at [www.nvent.com](http://www.nvent.com) and from your nVent customer service representative. Improper installation, misuse, misapplication or other failure to completely follow nVent's instructions and warnings may cause product malfunction, property damage, serious bodily injury and death and/or void your warranty.



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